

**BALANCE HIGH DENSITY
110 IDC TERMINAL BLOCK**

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CROSS-REFERENCE TO RELATED APPLICATION(S)

The subject application claims the benefit of U.S. Provisional Application Serial No. 60/288,156 filed May 2, 2001, the disclosure of which is herein incorporated by reference.

10

BACKGROUND OF THE DISCLOSURE

1. Technical Field

The present disclosure relates to devices for interfacing with high frequency data transfer media and, more particularly, to insulation displacement contact (“IDC”) devices, such as those that are used as interface connectors for Unshielded Twisted Pair (“UTP”) media, that advantageously compensate for and reduce electrical noise.

2. Background Art

In data transmission, the signal originally transmitted through the data transfer media is not necessarily the signal received. The received signal will consist of the original signal after being modified by various distortions and additional unwanted signals that affect the original signal between transmission and reception. These distortions and unwanted signals are commonly collectively referred to as “electrical noise,” or simply “noise.” Noise is a primary limiting factor in the performance of a communication system. Many problems may arise from the existence of noise in connection with data transmissions, such as data errors, system malfunctions and/or loss of the intended signals.

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The transmission of data, by itself, generally causes unwanted noise. Such internally generated noise arises from electromagnetic energy that is induced by the electrical energy in the individual signal-carrying lines within the data transfer media and/or data transfer connecting devices, such electromagnetic energy radiating onto or

5 toward adjacent lines in the same media or device. This cross coupling of electromagnetic energy (i.e., electromagnetic interference or EMI) from a “source” line to a “victim” line is generally referred to as “crosstalk.”

Most data transfer media consist of multiple pairs of lines bundled together. Communication systems typically incorporate many such media and connectors for data

10 transfer. Thus, there inherently exists an opportunity for significant crosstalk interference.

Crosstalk can be categorized in one of two forms. Near end crosstalk, commonly referred to as NEXT, arises from the effects of near field capacitive (electrostatic) and inductive (magnetic) coupling between source and victim electrical transmissions. NEXT increases the additive noise at the receiver and therefore degrades the signal to noise ratio

15 (SNR). NEXT is generally the most significant form of crosstalk because the high-energy signal from an adjacent line can induce relatively significant crosstalk into the primary signal. The other form of crosstalk is far end crosstalk, or FEXT, which arises due to capacitive and inductive coupling between the source and victim electrical devices at the far end (or opposite end) of the transmission path. FEXT is typically less of an issue

20 because the far end interfering signal is attenuated as it traverses the loop.

Characteristics and parameters associated with electromagnetic energy waves can be derived by Maxwell's wave equations. In unbounded free space, a sinusoidal disturbance propagates as a transverse electromagnetic wave. This means that the electric field vectors are perpendicular to the magnetic field vectors lying in a plane perpendicular

to the direction of the wave. As a result, crosstalk generally gives rise to a waveform shaped differently than the individual waveform(s) originally transmitted.

Unshielded Twisted Pair cable or UTP is a popular and widely used type of data transfer media. UTP is a very flexible, low cost media, and can be used for either voice or data communications. In fact, UTP is rapidly becoming the *de facto* standard for Local Area Networks (“LANs”) and other in-building voice and data communications applications. In a UTP, a pair of copper wires generally form the twisted pair. For example, a pair of copper wires with diameters of 0.4-0.8 mm may be twisted together and wrapped with a plastic coating to form a UTP. The twisting of the wires increases the noise immunity and reduces the bit error rate (BER) of the data transmission to some degree. Also, using two wires, rather than one, to carry each signal permits differential signaling to be used. Differential signaling is generally more immune to the effects of external electrical noise.

The non-use of cable shielding (e.g., a foil or braided metallic covering) in fabricating UTP generally increases the effects of outside interference, but also results in reduced cost, size, and installation time of the cable and associated connectors. Additionally, non-use of cable shielding in UTP fabrication generally eliminates the possibility of ground loops (i.e., current flowing in the shield because of the ground voltage at each end of the cable not being exactly the same). Ground loops may give rise to a current that induces interference within the cable, interference against which the shield was intended to protect.

The wide acceptance and use of UTP for data and voice transmission is primarily due to the large installed base, low cost and ease of new installation. Another important feature of UTP is that it can be used for varied applications, such as for Ethernet, Token Ring, FDDI, ATM, EIA-232, ISDN, analog telephone (POTS), and other types of

communication. This flexibility allows the same type of cable/system components (such as data jacks, plugs, cross-patch panels, and patch cables) to be used for an entire building, unlike shielded twisted pair media (“STP”).

At present, UTP is being used for systems having increasingly higher data rates.

- 5 Since demands on networks using UTP systems (e.g., 100Mbit/s and 1200Mbit/s transmission rates) have increased, it has become necessary to develop industry standards for higher system bandwidth performance. Systems and installations that began as simple analog telephone service and low speed network systems have now become high speed data systems. As the speeds have increased, so too has the noise.
- 10 The ANSI/TIA/EIA 568A standard defines electrical performance for systems that utilize the 1 to 100 MHz frequency bandwidth range. Exemplary data systems that utilize the 1-100 MHz frequency bandwidth range include IEEE Token Ring, Ethernet10Base-T and 100Base-T. EIA/TIA-568 and the subsequent TSB-36 standards define five categories, as shown in the following Table, for quantifying the quality of the cable (for example, only Categories 3, 4, and 5 are considered "datagrade UTP").
- 15

Table

<u>Category</u>	<u>Characteristic specified up to (MHz)</u>	<u>Various Uses</u>
1	None	Alarm systems and other non-critical applications
2	None	Voice, EIA-232, and other low speed data
3	16	10BASE-T Ethernet, 4-Mbits/s Token Ring, 100BASE-T4, 100VG-AnyLAN, basic rate ISDN. Generally the minimum standard for new installations.
4	20	16-Mbits/s Token Ring. Not widely used.
5	100	TP-PMD, SONet, OC-3 (ATM), 100BASE-TX. The most popular for new data installations.

Underwriter's Laboratory defines a level-based system, which has minor

- 5 differences relative to the EIA/TIA-568's category system. For example, UL requires the characteristics to be measured at various temperatures. However, generally (for example), UL Level V (Roman numerals are used) is the same as EIA's Category 5, and cables are usually marked with both EIA and UL rating designations.

UTP cable standards are also specified in the EIA/TIA-568 Commercial Building

- 10 Telecommunications Wiring Standard, including the electrical and physical requirements for UTP, STP, coaxial cables, and optical fiber cables. For UTP, the requirements currently include:

- Four individually twisted pairs per cable
- Each pair has a characteristic impedance of 100 Ohms +/- 15% (when measured at frequencies of 1 to 16 MHz)
- 24 gauge (0.5106-mm-diameter) or optionally 22 gauge (0.6438 mm diameter) copper conductors are used

5 Additionally, the EIA/TIA-568 standard specifies the color coding, cable diameter, and other electrical characteristics, such as the maximum cross-talk (i.e., how much a signal in one pair interferes with the signal in another pair--through capacitive, inductive, and other types of coupling). Since this functional property is measured as how many 10 decibels (dB) quieter the induced signal is than the original interfering signal, larger numbers reflect better performance.

Category 5 cabling systems generally provide adequate NEXT margins to allow for the high NEXT associated with use of present UTP system components. Demands for higher frequencies, more bandwidth and improved systems (e.g., Ethernet 1000Base-T) on 15 UTP cabling, render existing systems and methods unacceptable. The TIA/EIA category 6 draft addendum related to new category 6 cabling standards illustrates heightened performance demands. For frequency bandwidths of 1 to 250 MHz, the draft addendum requires the minimum NEXT values at 100 MHz to be -39.9 dB and -33.1dB at 250 MHz for a channel link, and -54 dB at 100MHz and -46 dB at 250 MHz for connecting 20 hardware. Increasing the bandwidth for new category 6 (i.e., from 1 to 100 MHz in category 5 to 1 to 250 MHz in category 6) increases the need to review opportunities for further reducing system noise.

The standard IDC terminal block is configured and dimensioned so as to provide maximum compatibility and matability between various manufacturers, e.g., based on the

standard for 110C connecting block mechanical dimensions. Two types of offsets have been produced from the standard 110C connecting block dimensions.

Type one is the standard 110C connecting block style for UTP cable splicing which is a straight through contact design and does not add any compensation methods to reduce crosstalk noises. The standard 110C connecting block provides a straightforward approach for 110C connecting block, by alignment of lead frames is in an uniformed parallel pattern high NEXT and FEXT is produced for certain wire pairs that are side by side. The standard 110C connecting block style is defined by two lead frame wire electrical connecting areas, section one is the matable area for input wire contact and section two is the output wire contact which completes the electrical signal connecting. This alignment of lead frames in an uniformed parallel pattern produces increases in NEXT and FEXT noises as well as increases in wire pair impedance.

Type two is the standard FCC part 68.500 style for modular plug housing which uses either pair separation or metal shielding methods to reduce crosstalk noises. Using either pair separation or metal shielding typically requires increasing the physical size from the IDC standard dimensions. Signal compensation is not needed by this approach since the wire pair separation of greater than 0.075 inches alone will decrease electrical NEXT noises by at least 9 dB. However, this method of reducing pair to pair NEXT does not re-balance the FEXT nor the impedance in the wires, since the pair capacitance has been offset by the IDC lead frames. If used, the metal shield is typically inserted between two wire pair lead frames to reduce the adjacent side of each wire pairs coupling to each other. These various methods provide a non-compensation approach for IDC terminal block NEXT reduction, but not without increasing IDC size and/or expensively re-bending extra metal coupling units to remove crosstalk noises.

Methods of compensation methods for connecting hardware crosstalk noise reduction and controlling are also addressed in U.S. Patent No. 5,618,185 to Aekins, the subject matter of which is hereby incorporated herein by reference thereto.

In view of the increasing performance demands being placed on UTP systems, e.g.,

5 the implementation of category 6 standards, it would be beneficial to provide a device and/or methodology that reduces NEXT and FEXT noises associated with standard IDC terminal blocks in a simple and cost effective manner. These and other objectives are achieved through the advantageous insert devices and systems disclosed herein.

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SUMMARY OF THE DISCLOSURE

The present disclosure provides a device that reduces the crosstalk NEXT and FEXT noises in IDC terminal blocks for a data/voice communication systems. A printed circuit board (“PCB”) with the proper balance coupling is incorporated in the block to reduce noise and re-balance the signal without negatively impacting the impedance

15 characteristics of the wire pairs in a simple and low cost manner. The electrical noise is reduced by the positional relationship of signals during passage through the PCB which advantageously results in signal feedback reactances that are used to compensate for pair to pair NEXT, FEXT and impedance.

In summary, the present disclosure is directed to providing a device for reducing

20 electrical noise during the transfer of data signals between media having a plurality of electrically conductive signal carrying elements.

In one embodiment, the device includes a dielectric support member, a means for receiving and transmitting signals from the signal carrying elements and a means for using the signals themselves to produce a capacitance which reduces the electrical noise. In one

25 aspect, the means for receiving and transmitting signals from the signal elements disposed

on the support member is a plurality of electrically conductive ports in electrical communication with the signal elements. Additionally, the means for using the signals to produce a capacitance may take the form of a plurality of elongated electrically conductive members in a close positional relationship or pattern with respect to each other.

5 The present disclosure additionally embodies a device for reducing crosstalk noise in an insulation displacement contact connectable with media having a plurality of signal carrying elements with positive and negative polarity data signals. In one aspect, this embodiment includes a dielectric support member and a plurality of elongated electrically conductive members disposed on the support member. The conductive members are in
10 electrical communication with the insulation displacement contact for receiving the data signals, and in a positional relationship with respect to each to produce a capacitance for reducing the crosstalk noise. Preferably, one or more elongated members are associated with only one signal carrying element. It is also preferable to have a greater amount of elongated members associated with signal carrying elements of like polarities to be in
15 positional relationships which form a capacitance, rather than the elongated members associated with signal carrying elements of opposing polarities. The deliberate positioning of members of the same polarity to form a capacitance strengthens the respective signals in the members. Preferably, the elongated members are all substantially the same size and distance from each other.

20 In another embodiment, a system for reducing electrical noise during the transfer of data signals between media cables having signal carrying elements of negative and positive polarity is disclosed. The system includes an IDC in electrical communication with communication ports on a PCB. The ports are in turn in electrical communication with electrically conductive traces having portions in positional relationships with respect to
25 each other for forming a capacitance to reduce electrical noise in the associated signals.

Preferably, there are eight communication ports which corresponds with standard 4 pair (8 wires) UTP cables.

For purposes of further illustrating this particular embodiment, it is assumed that communication ports one through eight are in communication with wires one through eight 5 in a standard UTP cable. Thus, the preferred arrangement is as follows: traces in communication with port three are in a positional relationship for forming a capacitance with traces in communication with port one and port five; traces in communication with port seven are in a positional relationship for forming a capacitance with traces in communication with port eight and port five; traces in communication with port six are in a 10 positional relationship for forming a capacitance with traces in communication with port four and port eight; and traces in communication with port four are in a positional relationship for forming a capacitance with traces in communication with port one and port two.

Preferably, the arrangement of traces produce a balanced voltage bridge of mutual 15 capacitor reactance to compensate for the electrical noise in the signals to the PCB.

These and other unique features of the systems, devices and methods of the present disclosure will become more readily apparent from the following description of the drawings taken in conjunction with the detailed description of preferred and exemplary embodiments.

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BRIEF DESCRIPTION OF THE DRAWINGS

So that those having ordinary skill in the art to which the subject disclosure appertains will more readily understand how to construct and employ the subject disclosure, reference may be had to the drawings wherein:

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Figure 1 is an exploded perspective view illustrating the arrangement of components in a standard 110 IDC terminal block;

5 Figure 2 is a top view of the standard IDC terminal block of Figure 1;

Figure 3 is a front view of the standard IDC terminal block of Figure 1;

10 Figure 4 is a perspective view illustrating the arrangement of wires in a standard four pair UTP cable;

15 Figure 5 is an exploded perspective view illustrating the arrangement of components in a exemplary balance high density 110 IDC terminal block constructed in accordance with the present disclosure;

20 Figure 6 is a cross-sectional view of the exemplary balance high density 110 IDC terminal block of Figure 5 taken along line 6-6;

Figure 7 is a cross-sectional view of the exemplary balance high density 110 IDC terminal block of Figure 5 taken along line 7-7;

25 Figure 8 is a top view of the exemplary balance high density 110 IDC terminal block of Figure 5;

Figure 9 is a top view of the first side of a PCB for use with an exemplary balance high density 110 IDC terminal block in accordance with the present disclosure;

Figure 10 is top view of the second side of the PCB for use with an exemplary balance high density 110 IDC terminal block of Figure 9; and

5 Figure 11 is a perspective view of the manner in which multiple 110 terminal blocks constructed in accordance with the present disclosure may be connected to a interconnecting wiring panel having input and output UTP cables spliced and installed on the blocks to complete the electrical connection for an UTP media system.

10 These and other features of the method of the subject disclosure will become more readily apparent to those having ordinary skill in the art from the following detailed description of preferred and exemplary embodiments.

DETAILED DESCRIPTION OF PREFERRED EMBODIMENT(S)

15 The following detailed description of preferred and/or exemplary embodiments of the present disclosure is intended to be read in the light of, or in context with, the preceding summary and background descriptions. Unless otherwise apparent, or stated, directional references, such as "up", "down", "left", "right", "front" and "rear", are intended to be relative to the orientation of a particular embodiment of the disclosure as shown in
20 the first numbered view of that embodiment. Also, a given reference numeral should be understood to indicate the same or a similar structure when it appears in different figures.

Exemplary devices in accordance with the present disclosure are directed to reducing the harmful effects of electrical noise which naturally occurs in signals during passage through data transfer cables and connecting components. In particular, the present

disclosure involves incorporating signal compensating devices into a new or existing component, such as the high density 110 IDC terminal block.

Figures 1-3 illustrate the general configuration of a standard 110 IDC terminal block 10 currently used in the field. The IDC housing 12 is constructed of a dielectric material and generally rectangular in shape. Housing 12 has a first cable engagement portion 14, a second cable engagement portion 16, a panel engagement portion 18, lead frame engagement port 20 and eight lead frame receiving slots 22. First and second cable engagement portions 14 and 16 provide locations for the connection of two cables with block 10 on opposing sides of housing 12. Second cable engagement portion 16 is located substantially within panel engagement portion 18, which serves to further secure the cable connection with engagement portion 16, as shown in Figure 11. The eight lead frame receiving slots 22 are accessible only through panel engagement portion 18.

Block 10 typically contains four pairs of elongated lead frames 24 which are configured and arranged to accept standard UTP 22-26 gauge wires. For the EIA T568B or T568A style configurations of category 5 and 6 UTP cabling, there are eight positions from four pairs of wires as shown in Figure 4. Lead frames 24 are constructed of an electrically conductive material and disposed in slots 22 within housing 12 to provide electrical communication between the first and second cable engagement portions 14 and 16. Each lead frame 24 has opposing first and second wire insulation cutting contact ends 26 and 28, which correspond in location with the first and second cable engagement portions 14 and 16 when lead frames 24 are secured in housing 12. Each lead frame 24 also has a hole 30 substantially adjacent to its middle portion which is adjacent the lead frame engagement port 20 upon installation in slots 22.

To assemble block 10, the lead frames 24 are inserted into receiving slots 22 within housing 12. First cable engagement portion 14 is configured to receive first contact end

26. Lead frames 24 are fully secured by a dielectric cover 32 configured to fit into lead frame engagement port 20. Cover 32 has eight pegs 34 disposed thereon which are inserted through peg receiving slots 36 in housing 12 and into holes 30 to fasten the eight lead frames 24 in position.

5 A significant portion, and in many instances, a majority of the coupled noise associated with the standard UTP four pair cable, such as cable 25 shown in Figure 4, arises from the adjacency of the paired arrangements. Additional coupled noise occurs due to the parallel arrangement of contacts in data transfer and UTP cable connecting components such as the IDC. In standard four pair UTP cables (such as cable 25), pair 1
10 includes wires 1 and 2, pair 2 includes wires 3 and 4, pair 3 includes wires 5 and 6 and pair 4 includes wires 7 and 8. Each wire in the pairs is of a different polarity, representing the different direction of signal transmission, and are referred to as “ring” (negative voltage) and “tip” (positive voltage). Thus, in a standard UTP cable, wires 1, 3, 5 and 7 are ring while wires 2, 4, 6 and 8 are tip.

15 Typically, the worst case for a UTP four pair cable is wires 2 through 7 because these wires are positioned adjacent wires with both transmitting and receiving signals or two opposing polarities. On a relative basis, the worst case NEXT noise in a 110 IDC terminal block is from an imbalance of coupled negative noise, meaning the noise is coupled unequally upon the adjacent pairs which also primarily effects wires 2-7. The
20 wires in the cable may create noise problems for other wires, but such problems are of significantly lesser magnitude because only one wire is the noise source.

Referring now to Figures 5-8, an exemplary high density 110 IDC terminal block 110 constructed in accordance with the present disclosure is illustrated. For purposes of describing the features of this embodiment, numbers 1-8 have been labeled on parts that

would be in electrical communication with wires 1-8 upon installation of a UTP cable with the block 110.

Instead of a cover 32 securing frames 24 with pegs 34, block 110 incorporates eight pins 38 constructed of an electrically conductive material which are inserted into slots 36.

- 5 Pins 38 contact and secure frames 24. Preferably, pins 38 are of the type known in the field as “dual compliant” pins which, when secured, provide a gas tight electrical connection which is comparable to direct metal soldering.

A printed circuit board (“PCB”) 40 having eight receiving ports 42 is physically and electrically connected with the opposing ends of pins 38. Thus, pins 38 provide a 10 mechanical connection and electrical communication between PCB 40 and frames 24. Preferably, and as shown, a cover 132 is placed over PCB 40 on block 110 to protect PCB 40 and pins 38. Cover 132 may be secured by any conventional means, such as a snap-fit arrangement or screws.

Figures 9 and 10 illustrate an exemplary embodiment of a PCB constructed in 15 accordance with the present disclosure. Pins 38 corresponding to wires 1-8 are inserted into communication ports 142 lined with a conductive material to permit communication of signals from wires 1-8 to PCB 140.

PCB 140 incorporates a balancing capacitive bridge circuitry that adds signal feedback to the appropriate wire pairs. In differentially signal driven systems, the signals 20 are typically equal in magnitude but have opposite polarity, that is, ring and tip as previously discussed. In a typical 110C connecting block one pair’s negative wire is adjacent another pair’s positive wire causing signal unbalance that increases NEXT and FEXT. In order to achieve proper circuit balance of NEXT noise vectors, the input to output victim lines can be described as a balance voltage bridge of mutual capacitor reactance. The output contains negative and positive mutual capacitance obtained from 25

coupling with other lead frames 24. Thus, to reduce the victim lines induced crosstalk noise, the output must be re-balanced to correspond with the input. PCB 140 serves to route the signals associated with the eight wires in electrically conductive members which induces feedback coupling that will either increase or decrease the signal magnitude

5 depending on their respective polarities to rebalance the signals.

Figure 9 depicts a first side 144 of PCB 140 having traces 146-157 constructed of an electrically conductive material disposed thereon. Figure 10 depicts a second side 158 of PCB 140 having traces 160-173 constructed of an electrically conductive material disposed thereon. The traces may be etched on PCB 140 or disposed by any other conventional method. Preferably, the traces are formed as elongated conductive strips of metal. The traces are in electrical communication with ports 142 to receive signals from wires 1-8. Portions of the traces are arranged in a positional relationship with respect to each other or other traces which is conducive to reducing and/or compensating for electrical noise. Preferably, the reduction and/or compensation of electrical noise is

10 accomplished by inducing coupling between the traces to counteract the coupling which occurred while the signal passed through cable 25 and into block 110. Coupling may be induced simply by aligning the traces adjacently on PCB 140.

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Preferably, each trace is of the same thickness and length, and there is an equal amount of separation between each trace, which aids in producing peak field coupling.

20 The type of coupling may be described as forward compensation or reverse compensation. Forward compensation refers to inducing coupling between traces associated with wires carrying the same polarity signals, that is, coupling is induced between traces associated with wires having ring polarity signals and likewise with traces associated with wires having tip polarity signals. Forward compensation typically increases the magnitude of

25 the coupled signal to reduce the unwanted electrical noise. Reverse compensation is

inducing coupling between traces associated with wires having opposing signals (i.e., ring and tip), which typically helps to balance the signals from wires which were not primarily effected by two adjacent wires, such as wires 1 and 8 in a standard UTP cable. Reverse compensation also helps remove any electrical noise that originated as a result of any non-
5 adjacent wires since all pairs have a percentage of coupled signals from each other.

Thus, on first side 144 in this embodiment, wire 1 is associated with trace 146 which is in a positional relationship to induce coupling with trace 148 associated with wire
3. Trace 147 associated with wire 2 is in a positional relationship to induce coupling with
trace 150 associated with wire 4. Trace 149 associated with wire 3 is in a positional
10 relationship to induce coupling with trace 152 associated with wire 5. Trace 151 associated
with wire 4 is in a positional relationship to induce coupling with trace 154 associated with
wire 6. Trace 153 associated with wire 5 is in a positional relationship to induce coupling
with trace 156 associated with wire 7. Trace 155 associated with wire 6 is in a positional
relationship to induce coupling with trace 157 associated with wire 8.

15 On second side 158 of PCB 140, trace 160 associated with wire 1 is in a positional
relationship to induce coupling with trace 163 associated with wire 3. Trace 161
associated with wire 1 is in a positional relationship to induce coupling with trace 165
associated with wire 4. The coupling between traces 161 and 165 provides reverse
compensation. Trace 162 associated with wire 2 is in a positional relationship to induce
20 coupling with trace 165 associated with wire 4. Trace 164 associated with wire 3 is in a
positional relationship to induce coupling with trace 167 associated with wire 5. Trace 166
associated with wire 4 is in a positional relationship to induce coupling with trace 169
associated with wire 6. Trace 168 associated with wire 5 is in a positional relationship to
induce coupling with trace 171 associated with wire 7. Trace 168 is also in a positional
25 relationship with trace 173 associated with wire 8 to provide for reverse compensation.

Trace 170 associated with wire 6 is in a positional relationship to induce coupling with trace 172 associated with wire 8.

In summary, the traces in PCB 140 re-balance the wire pairs by inducing both negative and positive coupling to the adjacent pair wires. For this embodiment, in adjacent pairs 1 and 2, the signal from wire 1 (negative) is coupled with the signal from wire 3 (negative) and the signal from wire 4 (positive) is coupled with the signals from wire 1 and wire 2 (positive). In adjacent pairs 2 and 3, the signal from wire 3 is coupled with the signal from wire 5 (negative) and the signal from wire 4 is coupled with the signal from wire 6 (positive). For adjacent pairs 3 and 4, the signal from wire 6 is coupled with the signal from wire 8 (positive) and the signal from wire 5 is coupled with the signals from wire 7 (negative) and the wire 8.

The capacitance symbols from a balance bridge are as follows:

-C23 equals IDC terminal block lead frame mutual capacitance of pairs 1 and 2;
C13 equals IDC terminal block lead frame mutual capacitance of pairs 1 and 3;
15 C14 equals IDC terminal block lead frame mutual capacitance of pairs 1 and 4;
C24 equals IDC terminal block lead frame mutual capacitance of pairs 2 and 4;
(providing that the interfacing plugs positive mutual capacitance equals the PCB negative mutual capacitance to complete the balance circuit.)

The circuit balance between source and victim will be as shown: $|C_{12}|_{\text{source}} =$

20 $|C_{34}|_{\text{victim}}$. The source signal $|C_{12}|$ induces an unwanted mutual capacitance $|C_{23}|$. If certain assumptions and theoretical percentages of the invention for source and victim line mutual capacitance's are introduced the formula evolves into:

$$|-1^{1/2}C_{23}| = |+1^{1/4}C_{13}| = -1/4C_{23} \text{ for one lead frame solving at like bridge terminals;}$$

$$|-C_{14}| = |+^{1/4}C_{24}| = 1/4C_{14}, \text{ for the other lead frame solving at like bridge terminals,}$$

25 for pair 1 being the signal source and pair 2 being the victim pair;

$|-1^{1/2} C_{23}| = |+11/4 C_{24}| = 1/4 C_{23}$ for one lead frame solving at like bridge terminals;

$|-C_{14}| = |-1/2 C_{14}|^+ |3/4 C_{1/3}| = -1/4 C_{14}$ for, the other lead frame solving at like bridge terminals,
for pair 2 being the signal source and pair 1 being the victim pair.

Currently existing standard IDC terminal blocks typically have NEXT performance

5 at 100 MHz of -47 dB, which fails the TIA category 6 connecting hardware specification
of -54 or below. Devices constructed or existing devices modified in accordance with the
present disclosure (Block 110) exceed the TIA category 6 connecting hardware
specification requirements, as illustrated in the NEXT noise comparison table shown
below.

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Table
NEXT Noise Comparison

Signal Frequency (MHz)	Category 6 Specification (-dB)	Block 110 (-dB)
1	75	93
10	74	83
16	70	78
20	68	77
31.25	64	73
61.5	58	65
100	54	60
155	50	57
200	48	56
250	46	54

As shown by the above table, a device constructed in accordance with the present
disclosure, which re-balances the unwanted coupled signals of the parallel lead frame wires
by utilizing a capacitive coupling PCB, provides an IDC terminal block which exceeds the
EIA category 6 connecting hardware electrical specifications. The PCB as disclosed
15 herein may also be incorporated as an insert for new or existing components. Thus, the
present disclosure provides a system, device and method for reducing crosstalk noise

without requiring new equipment or expensive re-wiring. An additional benefit resulting from the added capacitance is improved impedance. Impedance is typically increased by untwisting the wire pairs and the effect on the signals due to the parallel arrangement of the lead frames. The advantageous end result is an IDC terminal block that, among other

5 things, has lower NEXT, FEXT and impedance within its wire pairs.

Figure 11 illustrates multiple IDC terminal blocks, such as block 110, connected to an interconnecting wiring panel 74 via the panel engagement portions 18. Preferably, blocks 110 snap-fit onto a corresponding receiving portion on panel 74. Input cable 25 is connected with the first cable engagement portion 14 and output cable 76 is connected with

10 the second cable engagement portion 16 (not shown).

The features of the preferred embodiments depicted herein are in accordance with most standard wiring formations. The TIA/EIA commercial building standards have defined category 5e and 6 electrical performance parameters for higher bandwidth (100 up to 250MHz) systems. In category 5e and 6, the TIA/EIA wiring style is the preferred

15 formation and is generally followed throughout the cabling industry. However, it is within the purview of this disclosure to adapt the teachings herein for use with other wiring styles, such as those having different pairing arrangements or amounts of wires.

This method and system approach provides a more laboratory controlled product than other crosstalk reduction designs, which greatly improves design time, efficiency and

20 cost. This method and system approach also provides a way to effectively remove crosstalk in a very small amount of printed circuit board space.

Although the disclosed systems, devices and methods have been described with respect to preferred embodiments, it is apparent that modifications and changes can be made thereto without departing from the spirit and scope of the invention as defined by the

25 appended claims.